# Available in two types, 0.8mm height without stem or 1.5mm height with stem





Typical Specifications		
Items	Specifications	
Rating (max.)	50mA 12V DC	
Rating (min.)	10µA 1V DC	
Initial contact resistance	100mΩ max.	
Travel (mm)	0.25	

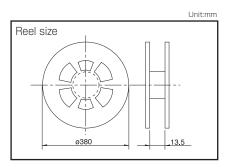
#### Product Line

Product No.	Operating	Operating direction (Fm 4 F) ( PC)		Stem	Minimum ord	er unit (pcs.)	Drawing
11000001110.	force	operating direction	(5mA 5V DC)	Oteni	Japan	Export	No.
SKQGAEE010	0.98N		500,000 cycles	Without stem	5,000	5,000	1
SKQGAAE010	1.57N	Top push					
SKQGACE010	2.55N		50,000 cycles				
SKQGAFE010	0.98N		500,000 cycles				
SKQGABE010	1.57N		100,000 cycles	With stem	4.000	4.000	2
SKQGADE010	2.55N		100,000 cycles	with Stelli	4,000	4,000	
SKQGAKE020	3.43N		IUU,UUU Cycles				

#### Packing Specifications

Taping

Series	Number of packages (pcs.)   1 reel 1 case / Japan 1 case / exort packing		Tape width (mm)	Export package measurements (mm)	
SKQGAA				()	()
SKQGAC SKQGAE	5,000	50,000	50,000	12	395×395×205
SKQGAB SKQGAD SKQGAF SKQGAK	4,000	40,000	40,000	12	333,333,203



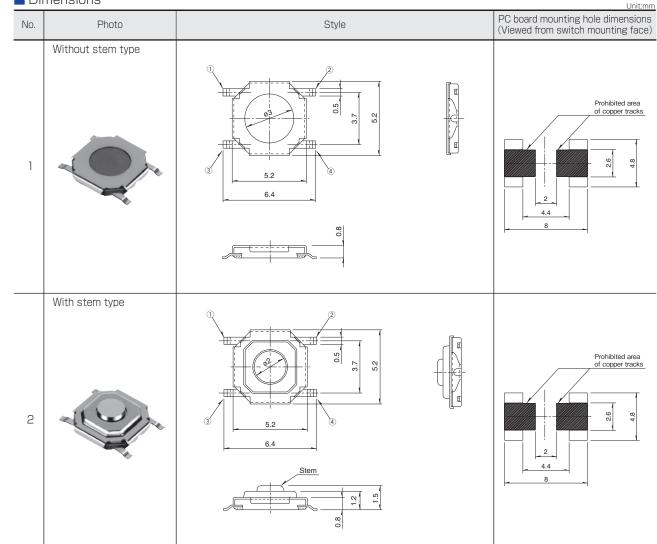
#### Note

For reels of 330mm diameter, please inquire.

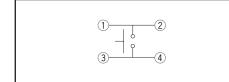


### SKQG 5.2mm Square Low-profile (Surface Mount Type)

Dimensions



#### Circuit Diagram





Feeling

Surface Mount Type

## **TACT Switch**<sup>™</sup> List of Varieties

	Туре				Surfac	e Mount			
	Series	SKSH	SKRW	SKRM	SKRB	SKRR	SKQG	SKTC	SKSK
	Photo		$\bigcirc$	۲	۲		-		
	Features		Low-	profile	1	Low-profile and long life	Low-profile	Double action	
	Water-proof	_	_	_	_	_	_	•	_
	Dust-proof	_	_	_	_	_	_	•	_
	IP standard	_	_	_	-	_	_	67 equivalency	_
Operatir	Top push	٠	•	•	•	•	•	•	٠
directio		_	_	_	_	_	_	_	_
	W	3.3				7.5		3.4	3.5
Dimensio (mm)	ons D	2.9	□3.7	□4.5	4.8	7	□5.2	2.2	3.2
()	Н	0.3	35	0.4	0.55	0.6	0.8/1.5	0.62	0.6
Operatio force coverag	2N to 3N	Ţ	Ţ	1	1	+		See the relevant respective descri	e product
	Travel (mm)	0.	15	0.15	5/0.2	0.	25	See the relevant respective production of the second secon	
G	round terminal	_	_	_	_	_		_	•
Operatin	ng temperature range	−30°C t	o +85°C	-	-40℃ to +85	jîC	-40°C to +90°C	−30°C to	o +85℃
A	utomotive use	_	_	_	•	_	0	—	_
Life Cycle		**3	2	2					
	Rating (max.) (Resistive load)	50mA 12V DC							
Electrical	Rating (min.) (Resistive load)		10µA 1V DC						
performance	Insulation resistance				100MΩ min.	100V DC 1min.			
	Voltage proof		100V AC 1min. 250V AC 1min. 100V AC 1min.					C 1min.	
Durability	Vibration		10 to 55 to 10Hz/min., the amplitude is 1.5mm for all the frequencies, in the 3 direction of X, Y and Z for 2 hours respectively						
Durubinty	Lifetime		Shall be in accordance with individual specifications.						
	Cold	-40°C 96h							
nvironmental performance	Dry heat	90°C 96h							
	Damp heat	60°C, 90 to 95%RH 96h							
	Page	210	211	212	213	214	215	217	218
ACT Sw	itch <sup>™</sup> Soldering Condition	ditions · · ·			D : H :	Width. The mo Depth. The mo Height. The mi	st outer dimens nimum dimensi	sion excluding to on if there are v 	erminal porti ariances. ••••26

1. The automotive operating temperature range to be individually discussed upon request.

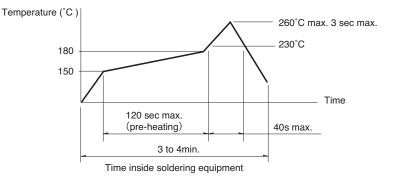
2. Indicates applicability to all products in the series, while  $\bigcirc$  indicates applicability to some products in the series.



#### Condition for Reflow

Available for Surface Mount Type.

- 1. Temperature measurement: Thermocouple  $\phi$  0.1 to 0.2 CA (K) or CC (T) at solder joints (copper foil surface). A heat resistive tape should be used to fix thermocouple.
- 2. Temperature profile



#### Notes

- The above temperature shall be measured of the top of switch. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the material, size, thickness of PC boards and others. The above-stated conditions shall also apply to switch surface temperatures.
- Soldering conditions differ depending on reflow soldering machines.
- Prior verification of soldering condition is highly recommended.

#### Conditions for Auto-dip

Available for Snap-in Type and Radial Type.

Items	Condition
Flux built-up	Mounting surface should not be exposed to flux
Preheating temperature	Ambient temperature of the soldered surface of PC board. 100°C max.
Preheating time	60s max.
Soldering temperature	260°C max.
Duration of immersion	Бs max.
Number of soldering	2times max.

#### SKHH, SKPD Series

Items	Condition
Flux built-up	Mounting surface should not be exposed to flux
Preheating temperature	Ambient temperature of the soldered surface of PC board. 110°C max.
Preheating time	60s max.
Soldering temperature	260°C max.
Duration of immersion	5s max.
Number of soldering	2times max.

#### SKQJ, SKQK, SKEG Series

Items	Condition
Flux built-up	Mounting surface should not be exposed to flux
Preheating temperature	Ambient temperature of the soldered surface of PC board. 100°C max.
Preheating time	45s max.
Soldering temperature	255°C max.
Duration of immersion	5s max.
Number of soldering	2times max.

#### Notes

1. Prevent flux penetration from the top side of the TACT Switch<sup>™</sup>.

- 2. Switch terminals and a PC board should not be coated with flux prior to soldering.
- 3. The second soldering should be done after the switch is stable with normal temperature.
- 4. Use the flux with a specific gravity of min 0.81.
- (EC-19S-8 by TAMURA Corporation, or equivalents.)

#### Manual Soldering

	<u> </u>
Items	Condition
Soldering temperature	350°C max.
Duration of soldering	Зs max.
Capacity of soldering iron	60W max.

#### SKHH, SKHW, SKRG, SKPD Series

Items	Condition
Soldering temperature	360°C max.
Duration of soldering	Зs max.
Capacity of soldering iron	60W max.

#### SKTD, SKTG, SKQJ, SKQK, SKEG Series

Items	Condition
Soldering temperature	350°C max.
Duration of soldering	Зs max.
Capacity of soldering iron	20W max.